RT/duroid® 6035HTC
High Frequency Laminate

RT/duroid® 6035HTC high frequency circuit materials are ceramic filled PTFE composites for use in high power RF and microwave applications.

With a thermal conductivity of almost 2.4 times the standard RT/duroid 6000 products, and copper foil (electrodeposited and reverse treat) with excellent long term thermal stability, RT/duroid 6035HTC laminates are an exceptional choice for high power applications.

Rogers advanced filler system enables excellent drill ability, reducing drilling costs as compared to standard high thermally conductive laminates which use alumina fillers.

Features/Benefits:

- High Thermal conductivity
  - Improved dielectric heat dissipation enables lower operating temperatures for high power applications
- Low loss tangent
  - Excellent high frequency performance
- Thermally stable low profile and reverse treat copper foil
  - Lower insertion loss and excellent thermal stability of traces
- Advanced filler system
  - Improved drill ability and extended tool life compared to alumina-containing circuit materials

Some Typical Applications:

- High power RF and microwave amplifiers
- Power amplifiers, couplers, filters, combiners, power dividers
At increasing power levels, Rogers measured the heat rise of a resistor placed on a microstrip circuit attached to a controlled heat sink. Thermal imaging was used to generate temperature rise data.

Comparison of WG-PTFE and RT/duroid 6035HTC laminate Thermal Images at 4 Watts:

![Thermal Images of WG-PTFE and RT/duroid 6035HTC](chart1)

**Heat Flow versus Temperature Rise**

**Dk = 3.5 Laminates**

**WG-PTFE**

**RT/duroid 6035HTC**

**Chart 1.** Four different 3.5 Dk laminate materials were tested, and the RT/duroid 6035HTC laminate most effectively dissipated heat away from the resistor to enable the lowest temperature rise.
Chart 2. Illustrates the stable copper peel strength maintained on 0.125" copper trace widths after multiple sixty-second exposures to 288°C (550°F) solder. Rogers matched copper foils to RT/duroid 6035HTC, which exhibit excellent thermal stability after multiple high temperature exposures enabling long-term reliability of circuitry for high power, high temperature applications.
<table>
<thead>
<tr>
<th>Property</th>
<th>Typical Value[^1]</th>
<th>Direction</th>
<th>Units</th>
<th>Condition</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dielectric Constant, $\varepsilon_r$ (Process)</td>
<td>3.50 ± 0.05</td>
<td>Z</td>
<td></td>
<td>10 GHz/23°C</td>
<td>IPC-TM-650, 2.5.5.5</td>
</tr>
<tr>
<td>Dielectric Constant, $\varepsilon_r$ (Design)</td>
<td>3.6</td>
<td>Z</td>
<td></td>
<td>8 GHz - 40 GHz</td>
<td>Differential Phase Length Method</td>
</tr>
<tr>
<td>Dissipation Factor</td>
<td>0.0013</td>
<td>Z</td>
<td>ppm/°C</td>
<td>10 GHz/23°C</td>
<td>IPC-TM-650, 2.5.5.5</td>
</tr>
<tr>
<td>Thermal Coefficient of $\varepsilon_r$</td>
<td>-66</td>
<td>Z</td>
<td>ppm/°C</td>
<td>-50°C to 150°C</td>
<td>mod IPC-TM-650, 2.5.5.5</td>
</tr>
<tr>
<td>Volume Resistivity</td>
<td>10°</td>
<td>MD</td>
<td>Ω•cm</td>
<td>COND A</td>
<td>IPC-TM-650, 2.5.17.1</td>
</tr>
<tr>
<td>Surface Resistivity</td>
<td>10°</td>
<td></td>
<td>Ω</td>
<td>COND A</td>
<td>IPC-TM-650, 2.5.17.1</td>
</tr>
<tr>
<td>Tensile Modulus</td>
<td>329 ± 244</td>
<td>MD</td>
<td>kpsi</td>
<td>40 hrs @ 23°C/50RH</td>
<td>ASTM D638</td>
</tr>
<tr>
<td>Dimensional Stability</td>
<td>-0.11 -0.08</td>
<td>CMD</td>
<td>mm/m</td>
<td>Thickness after etch +E4/105</td>
<td>IPC-TM-650, 2.4.39A</td>
</tr>
<tr>
<td>Coefficient of Thermal Expansion (-55 to 288 °C)</td>
<td>19</td>
<td>X</td>
<td>ppm/°C</td>
<td>23°C/50% RH</td>
<td>IPC-TM-650 2.4.41</td>
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<tr>
<td>Thermal Conductivity</td>
<td>1.44</td>
<td></td>
<td>W/m/K</td>
<td>80°C</td>
<td>ASTM C518</td>
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<tr>
<td>Moisture Absorption</td>
<td>0.06</td>
<td></td>
<td>%</td>
<td>D24/23</td>
<td>IPC-TM-650 2.6.2.1 ASTM D570</td>
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<tr>
<td>Density</td>
<td>2.2</td>
<td></td>
<td>gm/cm³</td>
<td>23°C</td>
<td>ASTM D-792</td>
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<tr>
<td>Copper Peel Strength</td>
<td>7.9</td>
<td>pli</td>
<td></td>
<td>20 sec.@ 288°C</td>
<td>IPC-TM-650 2.4.8</td>
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<tr>
<td>Flammability</td>
<td>V-0</td>
<td>pli</td>
<td></td>
<td></td>
<td>UL 94</td>
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<tr>
<td>Lead-Free Process Compatible</td>
<td>YES</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

[^1] Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.

[^2] The design $D_k$ is an average number from several different tested lots of material and on the most common thickness/s. If more detailed information is required, please contact Rogers Corporation. Refer to Rogers' technical paper “Dielectric Properties of High Frequency Materials” available at http://www.rogerscorp.com.

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### Standard Thickness

<table>
<thead>
<tr>
<th>Thickness</th>
<th>Panel Size</th>
<th>Copper Cladding</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.010&quot; (0.254mm)</td>
<td>12&quot; X 18&quot; (305 X 457mm)</td>
<td>½ oz. (18µm) Electrodeposited copper foil (HH/HH)</td>
</tr>
<tr>
<td>0.020&quot; (0.508mm)</td>
<td>24&quot; X 18&quot; (610 X 457mm)</td>
<td>1 oz. (35µm) Electrodeposited copper foil (H1/H1)</td>
</tr>
<tr>
<td>0.030&quot; (0.762mm)</td>
<td>½ oz. (18µm) Reverse treat copper foil (SH/SH)</td>
<td></td>
</tr>
<tr>
<td>0.060&quot; (1.524mm)</td>
<td>1 oz. (35µm) Reverse treat copper foil (S1/S1)</td>
<td></td>
</tr>
</tbody>
</table>

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